Supporting Information

Solvent-Free Fabrication of an Elastomeric Epoxy Resin Using Glycol Lignin from Japanese Cedar

Kenta Ono, [†] Osamu Tanaike,* [†] Ryo Ishii, [†] Takashi Nakamura, [†] Kazuhiro Shikinaka, [†] Takeo Ebina, [†]Thi Thi Nge[‡] and Tatsuhiko Yamada[‡]

[†] Research Institute for Chemical Process Technology, National Institute of Advanced Industrial Science and Technology (AIST), 4-2-1 Nigatake Miyagino-ku, Sendai, Miyagi 983-8551, Japan

[‡] Center for Advanced Materials, Forestry and Forest Products Research Institute,1 Matsunosato, Tsukuba, Ibaraki 305-8687, Japan

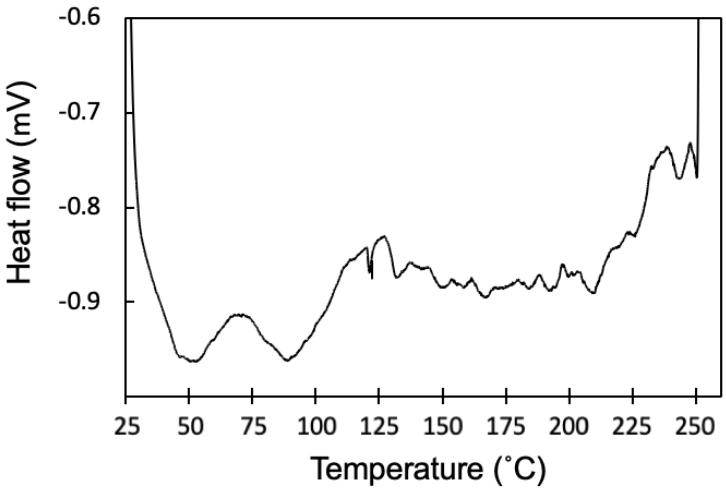

Figure S1. DSC profiles of the uncured GL-epoxy resin (GL400 content of 71.4 wt%) from room temperature to 250 °C (heating rate 5 °C/min) under a stream of N_2.

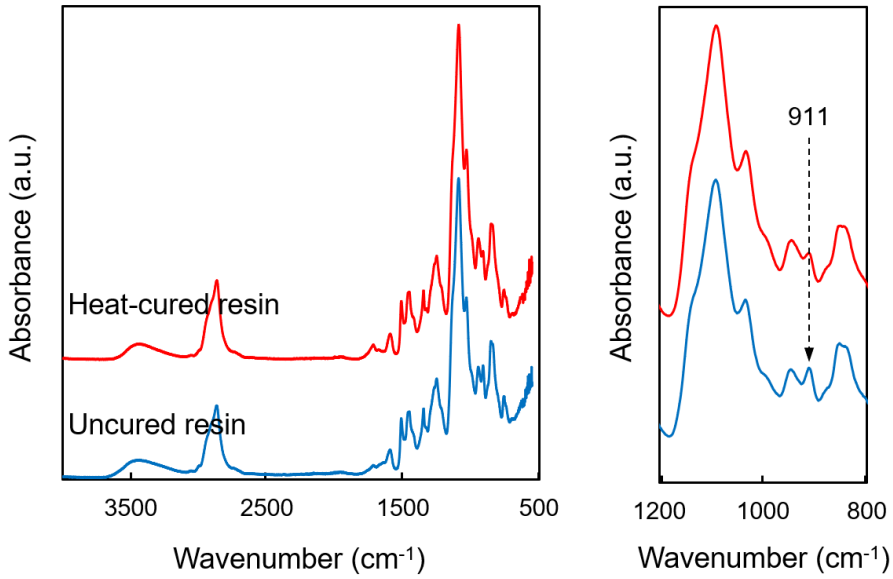

Figure S2. FTIR spectra (including detail of the epoxide absorption at 911 cm^{-1}) of the uncured GL-epoxy resin and heat-cured GL-epoxy resin (GL400 content of 41.2 wt%).